CMP PAD CONDITIONER

Advantages
- Strong diamond holding force: Chemical reaction + Mechanical contact
- Corrosion resistance: Carbide interface between diamond & bond material
- Longer lifetime: Utilization of edges by diamond face
- Maximized diamond chip pocket by high diamond exposure
  → Excellent conditioning efficiency and pad debris removal rate

Applications

<table>
<thead>
<tr>
<th>Polished materials</th>
</tr>
</thead>
<tbody>
<tr>
<td>New BSL type</td>
</tr>
<tr>
<td>(Double metal layer)</td>
</tr>
<tr>
<td>• Oxide CMP: BPSG, TEOS, PSG</td>
</tr>
<tr>
<td>• Metal CMP: Al, W, Cu</td>
</tr>
<tr>
<td>Electroplating type</td>
</tr>
<tr>
<td>• STI, PGI, Poly-si, TSV CMP → Cu, Poly-Si</td>
</tr>
</tbody>
</table>

Available Product Spec.

<table>
<thead>
<tr>
<th>Machines (model)</th>
<th>Pad cut rate</th>
</tr>
</thead>
<tbody>
<tr>
<td>AMAT Mirra/Reflexion</td>
<td>10 → 100 um/hr</td>
</tr>
<tr>
<td>Ebara (E-Flex200/300, EPO-222)</td>
<td></td>
</tr>
<tr>
<td>Novellus (Allegro, CMP200/300, Advantage 776)</td>
<td></td>
</tr>
<tr>
<td>Snedergah 605-SP, 450</td>
<td></td>
</tr>
<tr>
<td>Lam (Terra), etc.</td>
<td></td>
</tr>
</tbody>
</table>

Performance Data